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WANG et al.(10) **Pub. No.: US 2022/0377873 A1**(43) **Pub. Date: Nov. 24, 2022**(54) **CIRCUIT BOARD AND METHOD FOR
MANUFACTURING THE SAME****H05K 1/03** (2006.01)**H05K 3/46** (2006.01)(71) Applicants: **Avary Holding (Shenzhen) Co.,
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H05K 1/18 (2006.01)(57) **ABSTRACT**

A circuit board with improved heat dissipation function and a method for manufacturing the circuit board are provided. The circuit board includes a heat dissipation substrate, an insulating layer on the heat dissipation substrate, an electronic component, a base layer on the insulating layer, and a circuit layer on the base layer. The heat dissipation substrate includes a phase change structure and a heat conductive layer wrapping the phase change structure. The heat dissipation substrate defines a first through hole. The insulating layer defines a groove for receiving the electronic component. A second through hole is defined in the circuit layer, the base layer, and the insulating layer. A bottom of the second through hole corresponds to the heat conductive layer. A heat conductive portion is disposed in the second through hole.

